



40V 175°C DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

| BVDSS | Rds(ON) Max | I _D Max T _C = +25°C |
|-------|---------------------------------|--|
| 40V | 12.3mΩ @ V _{GS} = 10V | 46.2A |
| | 17.5mΩ @ V _{GS} = 4.5V | 38.7A |

Description and Applications

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, making it ideal for high efficiency power management applications.

- Power Management Functions
- **DC-DC Converters**

Features and Benefits

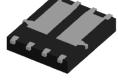
- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching, Test in Production-Ensures More Reliable and Robust End Application
- High Conversion Efficiency
- Low R_{DS(ON)} Minimizes On State Losses
- Low Input Capacitance
- Fast Switching Speed
- Wettable Flank for Improved Optical Inspection
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/
- An Automotive-Compliant Part is Available Under Separate Datasheet (DMTH4008LPDWQ)

Mechanical Data

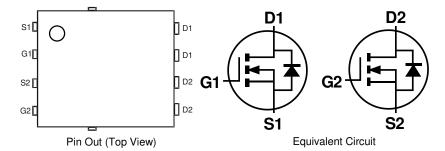
- Case: PowerDI[®]5060-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe. Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.097 grams (Approximate)

PowerDI5060-8/SWP (Type UXD)





Top View **Bottom View**



Ordering Information (Note 4)

| Part Number | Case | Packaging | |
|-----------------|------------------------------|-------------------|--|
| DMTH4008LPDW-13 | PowerDI5060-8/SWP (Type UXD) | 2,500/Tape & Reel | |

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. Notes:

- 2. See http://www.diodes.com/quality/lead_free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

Marking Information



) | | = Manufacturer's Marking TH4008LDW = Product Type Marking Code YYWW or YYWW = Date Code Marking YY or \overline{YY} = Year (ex: 20 = 2020) WW = Week (01 to 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit | |
|--|---|----------------|--------------|----|
| Drain-Source Voltage | V_{DSS} | 40 | V | |
| Gate-Source Voltage | V _{GSS} | ±20 | V | |
| Continuous Drain Current (Note 5) | T _A = +25°C T _A = +100°C | ID | 10.0 7.1 | А |
| Continuous Drain Current (Note 6) $ T_{C} = +25^{\circ}C $ $ T_{C} = +100^{\circ}C $ | | I _D | 46.2 32.7 | А |
| Pulsed Drain Current (10μs Pulse, Duty Cycle = 1%) | IDM | 184 | Α | |
| Maximum Continuous Body Diode Forward Current (Note 6) | ls | 43.7 | Α | |
| Pulsed Body Diode Forward Current (10µs Pulse, Duty Cycle = 1 | I _{SM} | 184 | Α | |
| Avalanche Current, L = 0.1mH | | las | 23.1 | Α |
| Avalanche Energy, L = 0.1mH | | Eas | 26.6 | mJ |

Thermal Characteristics

| Characteristic | Symbol | Value | Unit |
|--|----------|-------------|------|
| Total Power Dissipation (Note 5) | PD | 2.67 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | Reja | 56.6 | °C/W |
| Total Power Dissipation (Note 6) | PD | 39.4 | W |
| Thermal Resistance, Junction to Case (Note 6) | Rejc | 3.8 | °C/W |
| Operating and Storage Temperature Range | TJ, TSTG | -55 to +175 | °C |

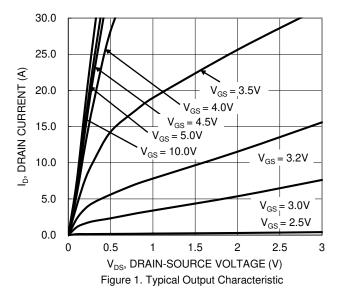
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

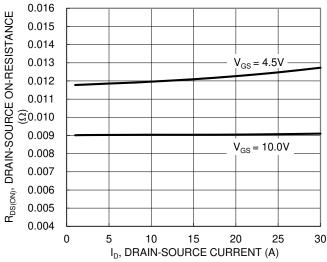
| Characteristic | Symbol | Min | Тур | Max | Unit | Test Condition | |
|------------------------------------|---------------------|-----|------|------|------|--|--|
| OFF CHARACTERISTICS (Note 7) | [-] | | - 71 | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | 40 | _ | _ | V | $V_{GS} = 0V, I_{D} = 250\mu A$ | |
| Zero Gate Voltage Drain Current | IDSS | _ | _ | 1 | μΑ | V _{DS} = 32V, V _{GS} = 0V | |
| Gate-Source Leakage | I _{GSS} | _ | _ | ±100 | nA | $V_{GS} = \pm 20V, V_{DS} = 0V$ | |
| ON CHARACTERISTICS (Note 7) | 1 | | • | | • | • | |
| Gate Threshold Voltage | V _{GS(TH)} | 1.2 | 1.88 | 2.3 | V | $V_{DS} = V_{GS}$, $I_D = 250\mu A$ | |
| Static Drain-Source On-Resistance | Dagger | _ | 9.5 | 12.3 | mΩ | V _{GS} = 10V, I _D = 20A | |
| Static Drain-Source On-Nesistance | RDS(ON) | _ | 11.9 | 17.5 | mΩ | V _{GS} = 4.5V, I _D = 10A | |
| Diode Forward Voltage | V _{SD} | _ | 0.9 | 1.2 | V | V _{GS} = 0V, I _S = 20A | |
| DYNAMIC CHARACTERISTICS (Note 8) | | | | • | | • | |
| Input Capacitance | Ciss | _ | 881 | _ | pF | | |
| Output Capacitance | Coss | _ | 496 | _ | pF | V _{DS} = 20V, V _{GS} = 0V, f = 1MHz | |
| Reverse Transfer Capacitance | Crss | _ | 19.5 | _ | pF | | |
| Gate Resistance | Rg | _ | 2.06 | _ | Ω | $V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$ | |
| Total Gate Charge (VGS = 10V) | Qg | _ | 12.3 | _ | nC | | |
| Total Gate Charge (VGS = 4.5V) | Qg | _ | 5.8 | _ | nC | V _{DS} = 20V, I _D = 20A | |
| Gate-Source Charge | Qgs | _ | 2.6 | _ | nC | | |
| Gate-Drain Charge | Qgd | _ | 1.6 | _ | nC | | |
| Turn-On Delay Time | t _{D(ON)} | _ | 3.82 | _ | ns | | |
| Turn-On Rise Time | tr | _ | 4.76 | _ | ns | V _{DD} = 20V, V _{GS} = 10V, | |
| Turn-Off Delay Time | tD(OFF) | _ | 12.6 | _ | ns | $R_g = 3\Omega$, $I_D = 20A$ | |
| Turn-Off Fall Time | tF | _ | 4.83 | _ | ns | | |
| Body Diode Reverse Recovery Time | trr | _ | 31.9 | _ | ns | 1 004 41/44 1004/ | |
| Body Diode Reverse Recovery Charge | Q _{RR} | _ | 25.0 | _ | nC | $I_F = 20A$, di/dt = 100A/ μ s | |

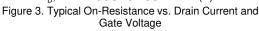
5. Device mounted on FR-4 substrate PC board, 2oz. copper, with thermal bias to bottom layer 1inch square copper plate.

^{5.} Device involved on the substance of board, 202. copper, with thermal blas to
6. Thermal resistance from junction to soldering point (on the exposed drain pad).
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to product testing.









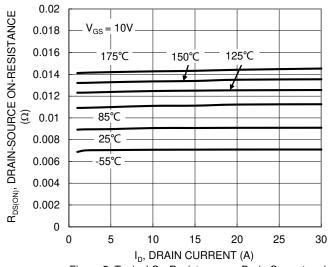
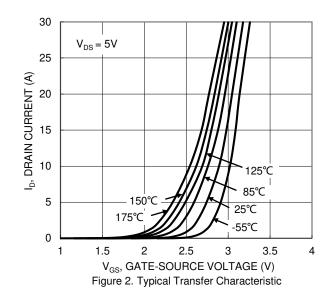
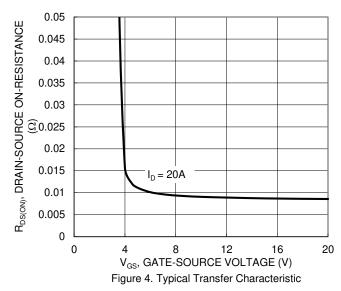


Figure 5. Typical On-Resistance vs. Drain Current and Temperature





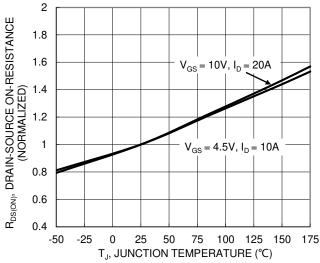


Figure 6. On-Resistance Variation with Temperature





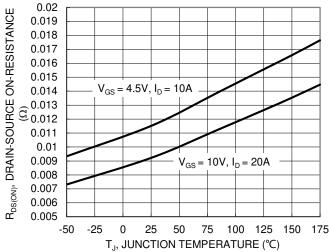
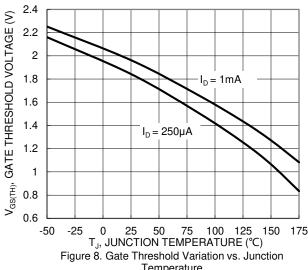
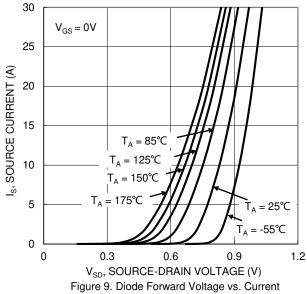
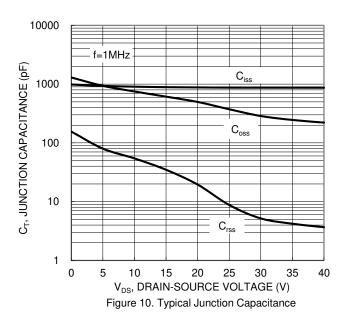


Figure 7. On-Resistance Variation with Temperature

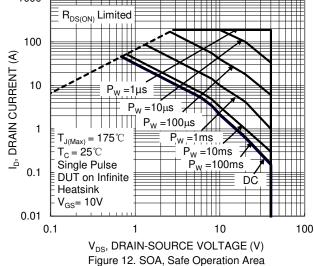


Temperature





1000 R_{DS(ON)} Limited 100 ID, DRAIN CURRENT (A) 10 1 $T_{J(Max)} = 175^{\circ}C$ T_C = 25°C Single Pulse 0.1 DUT on Infinite Heatsink V_{GS}= 10V 0.01 0.1



10 8 6 $V_{GS}(V)$ 4 $V_{DS} = 20V, I_{D} = 20A$ 2 0 3 12 0 15 Qg (nC)

Figure 11. Gate Charge

May 2020



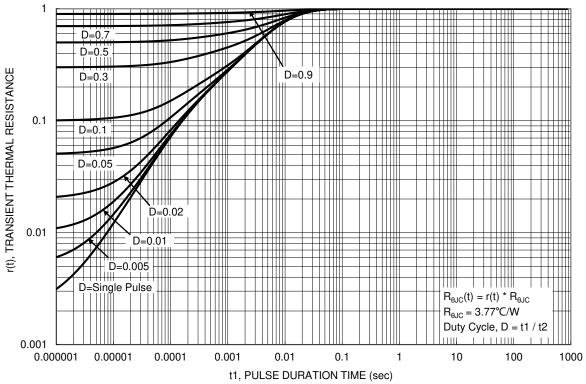


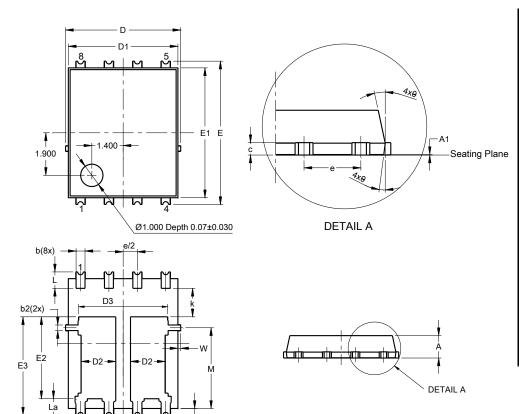
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8/SWP (Type UXD)

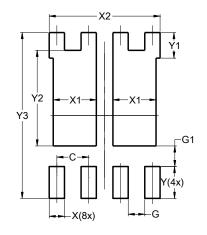


| PowerDI5060-8/SWP (Type UXD) | | | | |
|---------------------------------|-------|---------|--------|--|
| Dim | Min | Max | Тур | |
| Α | 0.90 | 1.10 | 1.00 | |
| A1 | 0.00 | 0.05 | | |
| b | 0.30 | 0.50 | 0.41 | |
| b2 | 0.20 | 0.35 | 0.25 | |
| b4 | (|).25REF | | |
| C | 0.230 | 0.330 | 0.277 | |
| D | | .15 BS0 | \sim | |
| D1 | 4.70 | 5.10 | 4.90 | |
| D2 | 1.46 | 1.66 | 1.55 | |
| D3 | 3.78 | 4.18 | 3.98 | |
| Е | 6 | .40 BS0 | | |
| E1 | 5.60 | 6.00 | 5.80 | |
| E2 | 3.46 | 3.86 | 3.66 | |
| E2a | 4.195 | 4.595 | 4.395 | |
| е | 1 | .27BSC | | |
| k | 1.05 | | 1 | |
| L | 0.635 | 0.835 | 0.735 | |
| La | 0.635 | 0.835 | 0.735 | |
| L1 | 0.200 | 0.400 | 0.300 | |
| М | 3.205 | 4.005 | 3.605 | |
| W | 0.025 | 0.225 | 0.125 | |
| θ | 10° | 12° | 11° | |
| θ1 | 6° | 8° | 7° | |
| All Dimensions in mm | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI5060-8/SWP (Type UXD)



| Dimensions | Value (in mm) | | |
|------------|------------------|--|--|
| С | 1.270 | | |
| G | 0.660 | | |
| G1 | 0.820 | | |
| X | 0.610 | | |
| X1 | 1.720 | | |
| X2 | 4.420 | | |
| Υ | 1.270 | | |
| Y1 | 1.020 | | |
| Y2 | 3.810 | | |
| Y3 | 6.610 | | |



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